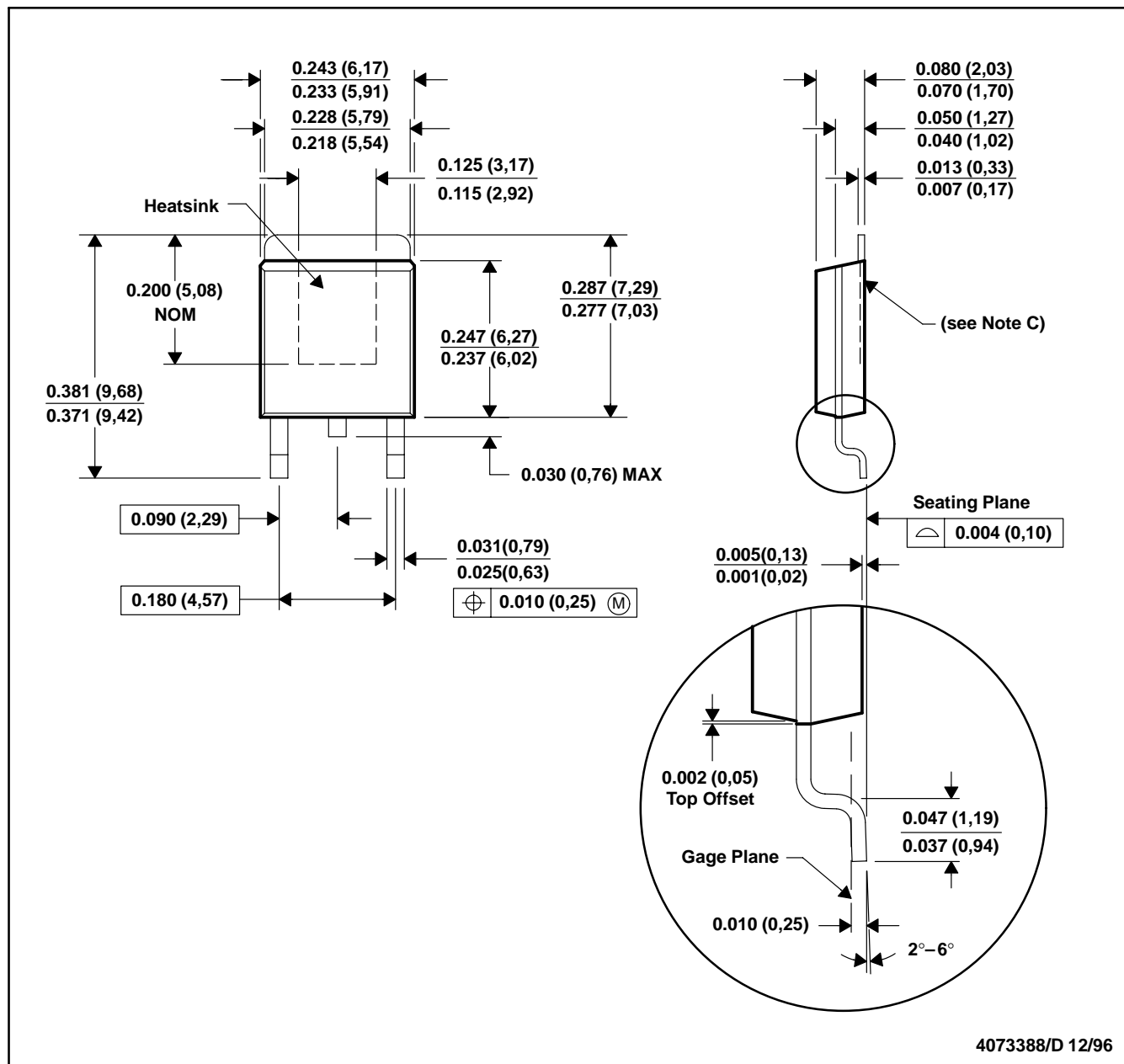


## KTP (R-PSFM-G2)

## PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. The heatsink area is approximately 28K sq mils.

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